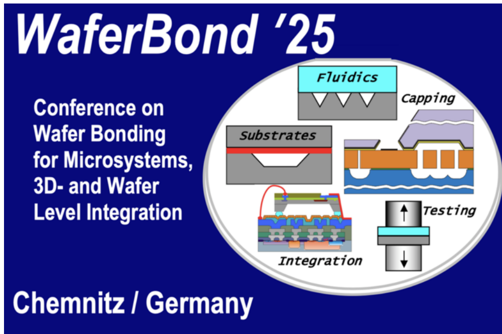

Local Chair by

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The International Conference on Wafer Bonding – WaferBond '25 will be held from December 3rd to 4th, 2025, in Chemnitz, Germany. It will be organized by ErzM-Technologies, locally chaired by Fraunhofer ENAS and technically chaired by Schmalkalden University of Applied Sciences.

2nd Call for Papers

You are invited to present your latest results in wafer bonding and chip to wafer bonding technologies and their applications in microsystems of any kind, to demonstrate the use of wafer bonding in complex devices, to share information regarding bonding equipment, bond testing methodology, and finally to meet your peers in this field for fruitful discussion.

The conference will cover all aspects of bonding wafers and comparable substrates, including chip to wafer bonding, from basic research to industrial applications, so any contribution about this is welcome. Beside this general approach the focus will be on the following topics this year:

- Fundamentals of wafer bonding and new developments in wafer and chip to wafer bonding
- Direct and surface activated wafer bonding at high and low temperatures
- Metal and glass-based bonding technologies
- Adhesive Wafer Bonding for permanent and temporary wafer bonding applications
- Hybrid bonding technologies
- System Integration by wafer and chip to wafer bonding and enabling new technologies and devices for modern applications for electronics and multiphysics systems
- Metrology for bonding processes and bonded wafer stacks
- Wafer and chip to wafer bonding in industrial processes: processes stability and reliability
- The future of (wafer) bonding, new ideas approaches and applications

There will be invited key notes especially for these exciting topics complemented by the contributions we hope to get from the wafer bonding community and from you.

Abstracts (max. 200 words) should be submitted by **April 30th, 2025 (extended deadline)**, to r.knechtel@hs-sm.de. The use of the abstract template is required. Authors will be informed of acceptance by **July 22nd, 2025**. Extended abstracts (2 pages) for proceedings are due **September 19th, 2025**.

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Maik Wiemer
Fraunhofer ENAS Chemnitz

Technical Chair
Roy Knechtel
Schmalkalden University of Applied Science

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